

Title (en)  
VERTICAL INTEGRATED COMPONENT, COMPONENT ARRANGEMENT AND METHOD FOR PRODUCTION OF A VERTICAL INTEGRATED COMPONENT

Title (de)  
VERTIKAL INTEGRIERTES BAUELEMENT, BAUELEMENT-ANORDNUNG UND VERFAHREN ZUM HERSTELLEN EINES VERTIKAL INTEGRIERTEN BAUELEMENTS

Title (fr)  
COMPOSANT INTEGRE VERTICAL, ENSEMBLE DE COMPOSANTS ET PROCEDE DE FABRICATION D'UN COMPOSANT INTEGRE VERTICAL

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Application  
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Abstract (en)  
[origin: WO2004040666A1] The invention relates to a vertical integrated component, a component arrangement and a method for production of a vertical integrated component. The vertical integrated component has a first electrical conducting layer (101), a mid layer (102), partly embodied from dielectric material on the first electrical conducting layer, a second electrical conducting layer (103) on the mid layer and a nanostructure (104) integrated in a through hole introduced in the mid layer with a first end section coupled to the first electrical conducting layer and a second end section coupled to the second electrical conducting layer. The mid layer comprises a third electrical conducting layer (105) between two adjacent dielectric partial layers (102a, 102b) the thickness of which is less than the thickness of at least one of the dielectric partial layers.

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